

IEEE 802.3cg 10SPE TF/802.3 10BP SG AdHoc meeting MAY 9TH 2018

Prepared by Peter Jones and Jon Lewis

Proposed Agenda:

1. Agenda/Admin Jon Lewis

Presentations posted at:

<http://www.ieee802.org/3/cg/public/adhoc/index.html>

Agenda/Admin Jon Lewis/Peter Jones:

Meeting began at 7:06am PT.

1. Reviewed the Attendance information related to the ad hoc(s).
2. Displayed pre & post-par slide deck, reviewed patent policy, participation conditions.
<https://development.standards.ieee.org/myproject/Public/mytools/mob/preparslides.pdf> (10BP)
<https://development.standards.ieee.org/myproject/Public/mytools/mob/slideset.ppt> (10SPE)
<https://mentor.ieee.org/802-ec/dcn/17/ec-17-0093-05-OPNP-ieee-802-participation-slide-ppt.ppt>
3. Made potentially essential patents call for 802.3cg – 10SPE
No-one responded (7:08AM PT).
4. Reminded participants to indicate full names and employer/affiliation correctly for the meeting minutes or email Jon Lewis, George Zimmerman or Peter Jones.
5. Did not ask for approval of minutes, will deal with this in Pittsburgh.

Presentations/Discussion.

Coupling attenuation and EMC considerations Dieter Schicketanz Reutlingen University

- Material presented and discussed

Proposed changes to D1.2 for Clauses 147 and 45 Jay Cordaro Broadcom

- Material presented and discussed

T1S scrambler & preamble update Piergiorgio Beruto CanovaTech

- Material presented and discussed

Meeting closed – 8:25 AM PT

Attendees (from Webex + emails)

Name	Employer	Affiliation	Attended 5/9
Amrit Gopal	Ford	Ford	y
Anadi Shukla	Cadence	Cadence	y
Aniruddha Phatak	Renesas	Renesas	y
Antonio Orzelli	Canova Tech	Canova Tech	y
Bernd Sostawa	MicroChip	MicroChip	y
Brett McClellan	Marvell	Marvell	y
Brian Franchuck	Emerson	Emerson	y
Christopher DiMinico	MC Communications/Panduit	MC Communications/ Panduit	y
Claude Gauthier	NXP	NXP	y
Craig Gunther	Harmen	Harmen	y
Dale Borgeson	ED Engineering	Emerson	y
Dave Hess	CordData	CordData	y
David Hoglund	Johnson Controls	Johnson Controls	y
David Law	HPE	HPE	y
Dayin Xu	Rockwell Automation	Rockwell Automation	y
Dieter Schicketanz	Consultant, Reutlingen University	Consultant, Reutlingen University	y
dixon chen	MicroChip	MicroChip	y
Eric DiBiaso	TE	TE	y
Gary Irwin	CommScope	CommScope	y
Geoff Thompson	GraCaSI S.A.	Independent	y
George Zimmerman	CME Consulting	ADI, APL Group, Aquantia, BMW, Cisco, Commscope	y
Gergely Huszak	Kone	Kone	y
Gian Marco Bo	Canova Tech	Canova Tech	y
Harald Zweck	Infineon	Infineon	y
Haysam Kadry	Ford	Ford	y
Helge Zinner	Continental Corp.	Continental Corp.	y
Henry Muyshondt	Microchip	Microchip	y
Hongming An	Microchip	Microchip	y
Jay Cordaro	Broadcom	Broadcom	y
Jens Gottron	Siemens	Siemens	y
Jon Lewis	Dell	Dell	y
Kirsten Matheus	BMW	BMW	y
Larry Matola	Aptiv	Aptiv	y
Les Farkas	Alarm.com	Alarm.com	y

Maris Graube	Relcom Inc.	Relcom Inc.	y
Mark Bohm	Microchip	Microchip	y
Martin Miller	Microchip	Microchip	y
Masood Shariff	CommScope	CommScope	y
Matthias Fritsche	HARTING Electronics GmbH	HARTING Electronics GmbH	y
Matthias Jaenecke	Yazaki	Yazaki	y
Mehmet Tazebay	Broadcom	Broadcom	y
Michael Rentschler	MicroChip	MicroChip	y
Michal Brychta	Analog Devices	Analog Devices	y
Mick McCarthy	Analog Devices	Analog Devices	y
Nicola Scantamburlo	Canova Tech	Canova Tech	y
Oisín Ó Cuanacháin	Analog Devices	Analog Devices	y
Paul Vanderlaan	Berk-Tek	Berk-Tek	y
Peter Wu	Marvell	Marvell	y
Phillip Brownele	TDK	TDK	y
Qing Xu	Belden	Belden	y
Steffen Graber	Pepperl+Fuchs	Pepperl+Fuchs	y
Sujan Pandey	NXP	NXP	y
Tim Baggett	Microchip	Microchip	y
Venkat Iyer	Microchip	Microchip	y
Attendees			54